

REVISIONS																			
LTR	DESCRIPTION										DATE (YR-MO-DA)				APPROVED				
A	Update drawing to the latest requirements of MIL-PRF-38534. -gc										21-06-07				James R. Eschmeyer				

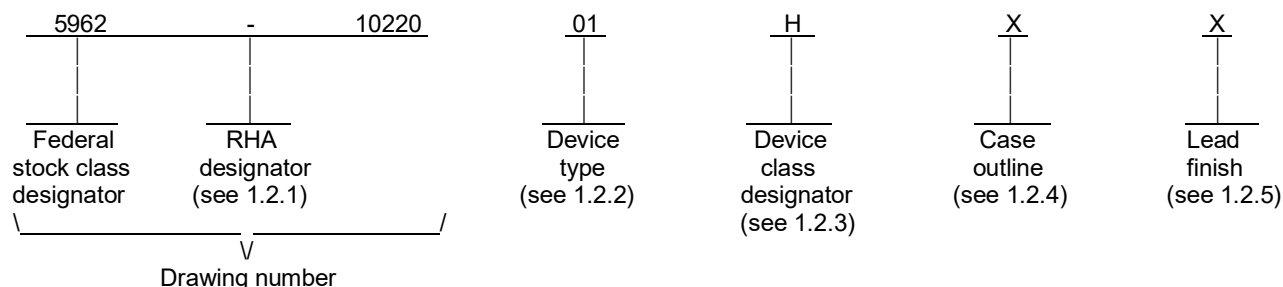


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REV STATUS OF SHEETS	REV			A	A	A	A	A	A	A	A	A	A	A	A	A			
	SHEET			1	2	3	4	5	6	7	8	9	10	11					
PMIC N/A				PREPARED BY Steve L. Duncan						DLA LAND AND MARITIME COLUMBUS, OHIO 43218-3990 https://www.dla.mil/LandandMaritime									
STANDARD MICROCIRCUIT DRAWING THIS DRAWING IS AVAILABLE FOR USE BY ALL DEPARTMENTS AND AGENCIES OF THE DEPARTMENT OF DEFENSE AMSC N/A				CHECKED BY Greg Cecil															
				APPROVED BY Charles F. Saffle															
				DRAWING APPROVAL DATE 13-02-21															
				REVISION LEVEL A						SIZE A	CAGE CODE 67268	5962-10220							
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1. SCOPE

1.1 Scope. This drawing documents five product assurance classes as defined in paragraph 1.2.3 and MIL-PRF-38534. A choice of case outlines and lead finishes which are available and are reflected in the Part or Identifying Number (PIN). When available, a choice of radiation hardness assurance levels are reflected in the PIN.

1.2 PIN. The PIN is as shown in the following example:



1.2.1 Radiation hardness assurance (RHA) designator. RHA marked devices meet the MIL-PRF-38534 specified RHA levels and are marked with the appropriate RHA designator. A dash (-) indicates a non-RHA device.

1.2.2 Device type(s). The device type(s) identify the circuit function as follows:

<u>Device type</u>	<u>Generic number</u>	<u>Circuit function</u>
01	15313-DESC	Nuclear Event Detector

1.2.3 Device class designator. This device class designator is a single letter identifying the product assurance level. All levels are defined by the requirements of MIL-PRF-38534 and require QML Certification as well as qualification (Class H, K, and E) or QML Listing (Class G and D). The product assurance levels are as follows:

<u>Device class</u>	<u>Device performance documentation</u>
K	Highest reliability class available. This level is intended for use in space applications.
H	Standard military quality class level. This level is intended for use in applications where non-space high reliability devices are required.
G	Reduced testing version of the standard military quality class. This level uses the Class H screening and In-Process Inspections with a possible limited temperature range, manufacturer specified incoming flow, and the manufacturer guarantees (but may not test) periodic and conformance inspections (Group A, B, C and D).
E	Designates devices which are based upon one of the other classes (K, H, or G) with exception(s) taken to the requirements of that class. These exception(s) must be specified in the device acquisition document; therefore the acquisition document should be reviewed to ensure that the exception(s) taken will not adversely affect system performance.
D	Manufacturer specified quality class. Quality level is defined by the manufacturers internal, QML certified flow. This product may have a limited temperature range.

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1.2.4 Case outline(s). The case outline(s) are as designated in MIL-STD-1835 and as follows:

<u>Outline letter</u>	<u>Descriptive designator</u>	<u>Terminals</u>	<u>Package style</u>
X	See figure 1	14	Dual-in-line package

1.2.5 Lead finish. The lead finish is as specified in MIL-PRF-38534.

1.3 Absolute maximum ratings. ^{1/}

Supply voltage at pins 6, 11, 12 and 14 with respect to ground, pin 7	+7.0 V dc
Supply voltage at pin 1 with respect to ground, pin 7	+20.0 V dc
Supply voltage at pin 8 with respect to ground, pin 7	+25.0 V dc
Storage temperature range (T _A)	-65°C to +150°C

1.4 Recommended operating conditions.

Supply voltage range (V _H)	+4.5 V dc to +5.5 V dc
Bias Supply voltage range (V _B)	+4.5 V dc to +5.5 V dc
Operating temperature range (T _A)	-55°C to +125°C

2. APPLICABLE DOCUMENTS

2.1 Government specification, standards, and handbooks. The following specification, standards, and handbooks form a part of this drawing to the extent specified herein. Unless otherwise specified, the issues of these documents are those cited in the solicitation or contract.

DEPARTMENT OF DEFENSE SPECIFICATIONS

MIL-PRF-38534 - Hybrid Microcircuits, General Specification for.

DEPARTMENT OF DEFENSE STANDARDS

MIL-STD-883 - Test Method Standard Microcircuits.
MIL-STD-1835 - Interface Standard for Electronic Component Case Outlines.

DEPARTMENT OF DEFENSE HANDBOOKS

MIL-HDBK-103 - List of Standard Microcircuit Drawings.
MIL-HDBK-780 - Standard Microcircuit Drawings.

(Copies of these documents are available online at <https://quicksearch.dla.mil>)

2.2 Order of precedence. In the event of a conflict between the text of this drawing and the references cited herein, the text of this drawing takes precedence. Nothing in this document, however, supersedes applicable laws and regulations unless a specific exemption has been obtained.

^{1/} Stresses above the absolute maximum ratings may cause permanent damage to the device. Extended operation at the maximum levels may degrade performance and affect reliability.

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3. REQUIREMENTS

3.1 Item requirements. The individual item performance requirements for device classes D, E, G, H, and K shall be in accordance with MIL-PRF-38534. Compliance with MIL-PRF-38534 shall include the performance of all tests herein or as designated in the device manufacturer's Quality Management (QM) plan or as designated for the applicable device class. The manufacturer may eliminate, modify or optimize the tests and inspections herein, however the performance requirements as defined in MIL-PRF-38534 shall be met for the applicable device class. In addition, the modification in the QM plan shall not affect the form, fit, or function of the device for the applicable device class.

3.2 Design, construction, and physical dimensions. The design, construction, and physical dimensions shall be as specified in MIL-PRF-38534 and herein.

3.2.1 Case outline(s). The case outline(s) shall be in accordance with 1.2.4 herein and figure 1.

3.2.2 Terminal and Burn-in connections. The terminal connections shall be as specified in figure 2, which also includes burn-in connections.

3.2.3 Truth table(s). The truth table(s) shall be as specified in table III.

3.3 Electrical performance characteristics. Unless otherwise specified herein, the electrical performance characteristics are as specified in table I and shall apply over the full specified operating temperature range.

3.4 Electrical test requirements. The electrical test requirements shall be the subgroups specified in table II. The electrical tests for each subgroup are defined in table I.

3.5 Marking of device(s). Marking of device(s) shall be in accordance with MIL-PRF-38534. The device shall be marked with the PIN listed in 1.2 herein. In addition, the manufacturer's vendor similar PIN may also be marked.

3.6 Data. In addition to the general performance requirements of MIL-PRF-38534, the manufacturer of the device described herein shall maintain the electrical test data (variables format) from the initial quality conformance inspection group A lot sample, for each device type listed herein. Also, the data should include a summary of all parameters manually tested, and for those which, if any, are guaranteed. This data shall be maintained under document revision level control by the manufacturer and be made available to the preparing activity (DLA Land and Maritime -VA) upon request.

3.7 Certificate of compliance. A certificate of compliance shall be required from a manufacturer in order to supply to this drawing. The certificate of compliance (original copy) submitted to DLA Land and Maritime -VA shall affirm that the manufacturer's product meets the performance requirements of MIL-PRF-38534 and herein.

3.8 Certificate of conformance. A certificate of conformance as required in MIL-PRF-38534 shall be provided with each lot of microcircuits delivered to this drawing.

4. VERIFICATION

4.1 Sampling and inspection. Sampling and inspection procedures shall be in accordance with MIL-PRF-38534 or as modified in the device manufacturer's Quality Management (QM) plan. The modification in the QM plan shall not affect the form, fit, or function as described herein.

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TABLE I. Electrical performance characteristics.

Parameter	Symbol	Conditions $\frac{1}{2} \frac{3}{4} \frac{5}{5}$ $-55^{\circ}\text{C} \leq T_A \leq +125^{\circ}\text{C}$ V_L and $V_H = 4.5 \text{ V to } 5.5 \text{ V}$ unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
Standby Supply Current	I_H	Supply voltage $V_H = 5.5 \text{ V}$, TEST Input = $0.00 \text{ V to } 0.05 \text{ V}$, NFR Input = $4.5 \text{ V to } 5.5 \text{ V}$, FR Input = $0.00 \text{ V to } 0.05 \text{ V}$, NED and NEF outputs high ($> 4.5 \text{ V}$)	1, 2, 3	01		2.0	mA
Flag Set Supply Current	I_H	$V_H = 5.5 \text{ V}$, NED output high ($> 4.5 \text{ V}$) and NEF output low ($< 0.5 \text{ V}$)	1, 2, 3	01		6.0	mA
Operational Supply Current	I_H	$V_H = 5.5 \text{ V}$, NED and NEF outputs low ($< 0.5 \text{ V}$)	1, 2, 3	01		15.0	mA
Output Leakage Current	I_L	Output Pull-up Supply $V_L = 20.0 \text{ V}$, NED and NEF outputs high ($> 4.5 \text{ V}$)	1, 2, 3	01		100	μA
Detector Leakage Current	I_B	Detector bias voltage $V_B = 5.5 \text{ V}$, NED output high ($> 4.5 \text{ V}$), NEF output low ($< 0.5 \text{ V}$)	1, 2, 3	01		5.0	μA
Detector Forward Voltage	V_F	Forward current, $I_{TH} = 10 \text{ mA}$	1, 2, 3	01	0.25	1.0	V
Flag Reset (FR) Input Current low	I_{FR}	Flag reset voltage $V_{FR} = 0.7 \text{ V}$, $\underline{6}/$ R_{TH} not connected	1, 2, 3	01		1.0	mA
Flag Reset (FR) Input Current high	I_{FR}	Flag reset voltage $V_{FR} = 3.0 \text{ V}$, $\underline{6}/$ R_{TH} not connected	1, 2, 3	01		3.0	mA
Flag Reset (FR) Switching Voltage	V_{FRSW}	R_{TH} not connected $\underline{6}/$	9, 10, 11	01	0.7	3.0	V
Flag Reset Inverse (NFR) Input Current low	I_{NFR}	Flag reset inverse voltage $V_{NFR} = 0.7 \text{ V}$, R_{TH} not connected $\underline{6}/$	1, 2, 3	01		-3.0	mA
Flag Reset Inverse (NFR) Input Current high	I_{NFR}	Flag reset inverse voltage $V_{NFR} = 4.0 \text{ V}$, R_{TH} not connected $\underline{6}/$	1, 2, 3	01		-1.0	mA
Flag Reset Inverse (NFR) Switching Voltage	V_{NFRSW}	R_{TH} not connected $\underline{6}/$	9, 10, 11	01	0.7	2.0	V
TEST Input Current low	I_{TEST}	TEST voltage $V_{TEST} = 0.7 \text{ V}$	1, 2, 3	01		1.0	mA
TEST Input Current high	I_{TEST}	TEST voltage $V_{TEST} = 4.0 \text{ V}$	1, 2, 3	01		4.0	mA
TEST Input Switching Voltage	V_{TESTSW}		9, 10, 11	01	0.7	3.0	V

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Parameter	Symbol	Conditions 1/ 2/ 3/ 4/ 5/ -55°C ≤ T _A ≤ +125°C V _L and V _H = 4.5 V to 5.5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
NED Output Voltage high	V _{DOH}	V _L = 20V, NED output current I _O = -100μA	1, 2, 3	01	18.5		V
NED Output Voltage low	V _{DOL}	NED output current I _{OL} = 10 mA	1, 2, 3	01		0.6	V
NED Output Voltage low	V _{DOL}	NED output current I _{OL} = 20 mA	1, 2, 3	01		0.7	V
NEF Output Voltage high	V _{FOH}	V _L = 20 V, NEF output current I _O = -100 μA	1, 2, 3	01	18.5		V
NEF Output Voltage low	V _{FOL}	NEF output current I _{OL} = 10 mA	1, 2, 3	01		0.6	V
NEF Output Voltage low	V _{FOL}	NEF output current I _{OL} = 20 mA	1, 2, 3	01		0.7	V
TEST Input Pulse Width	t _{TEST}	V _{TEST} = 0 V to 4.0 V	9, 10, 11	01	250		ns
TEST Input to NED Output Delay	t _o	V _{TEST} = 0 V to 4.0 V duration 10 μs	9, 10, 11	01		10	μs
TEST Input to NEF Output Delay	t _q	V _{TEST} = 0 V to 4.0 V duration 10 μs	9, 10, 11	01		10	μs
FR Input Pulse Width	t _{FR}	V _{FR} = 0 V to 4.0 V	9, 10, 11	01	250		ns
FR Input to NEF Output Delay	t _r	V _{FR} = 0 V to 4.0 V duration 1 μs	9, 10, 11	01		1.0	μs
NFR Input Pulse Width	t _{NFR}	V _{NFR} = 5.0 V to 0.7 V	9, 10, 11	01	500		ns
NFR Input to NEF Output Delay	t _s	V _{NFR} = 5.0 V to 0.7 V duration 1 μs	9, 10, 11	01		1.0	μs
NED Output Delay	t _t	V _{RTH} = 0 V to 5.0 V duration 100 ns, pull-up resistor = 220 Ω	9, 10, 11	01		50	ns
NEF Output Delay	t _u	V _{RTH} = 0 V to 5.0 V duration 100 ns, pull-up resistor = 220 Ω	9, 10, 11	01		200	ns

See footnotes at end of table.

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TABLE I. Electrical performance characteristics - Continued.

Parameter	Symbol	Conditions <u>1/</u> <u>2/</u> <u>3/</u> <u>4/</u> <u>5/</u> -55°C ≤ T _A ≤ +125°C V _L and V _H = 4.5 V to 5.5 V unless otherwise specified	Group A subgroups	Device type	Limits		Unit
					Min	Max	
NED Output Pulse Width	t _{NED}	Supply voltage V _H = 4.5 V to 5.5 V, NED active when TEST input active - pulse duration timed from negative edge of TEST input	9, 10, 11	01	10	30	μs/nF
NED Output Pulse Width	t _{NED}	Supply voltage V _H = 4.95 V to 5.05 V, NED active when TEST input active - pulse duration timed from negative edge of TEST input	9, 10, 11	01	13	27	μs/nF

- 1/ All voltage measurements are made with respect to pin 7 (GND), unless otherwise specified.
- 2/ The definition of high and low voltage levels are: V_{OL} < 0.5 V, V_{OH} > 4.5 V, unless otherwise specified.
- 3/ V_B, NED and NEF pins not connected, unless otherwise specified.
- 4/ C_T = 47 nF +/-10% and connected to pins 4 and 5, unless otherwise specified.
- 5/ In standby mode (no nuclear event detected) both NED and NEF outputs and NFR input will be in the "high" state and TEST and FR input will be in the "low" state.
- 6/ R_{TH} = 180 Ω +/-2 Ω connected between pin 9 (RTH) and pin 7 (GND), unless otherwise specified.

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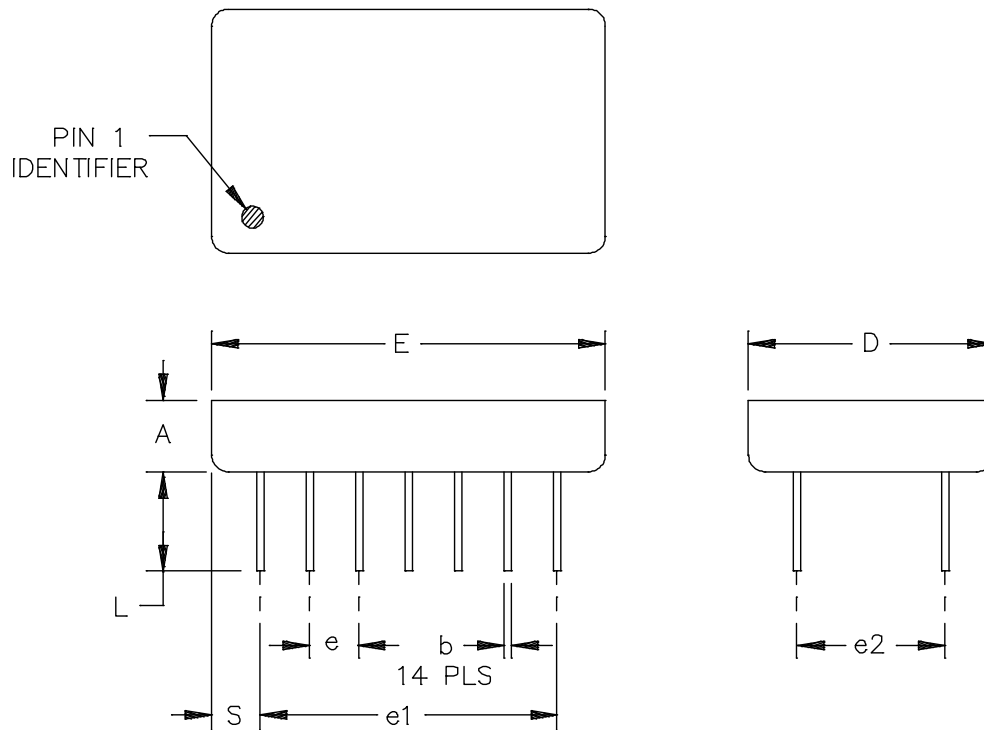
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Case outline X.



Symbol	Inches		Millimeters	
	Min	Max	Min	Max
A		.145		3.68
b	.016	.022	.41	.56
D	.490	.500	12.45	12.70
e	.100 BSC		2.54 BSC	
e1	.600 BSC		15.24 BSC	
e2	.295	.305	7.49	7.75
E	.790	.800	20.06	20.32
L	.195	.215	4.95	5.46
S	.095	.105	2.41	2.68

NOTES:

1. The U.S. preferred system of measurement is the metric SI. This item was designed using inch-pound units of measurement. In case of problems involving conflicts between the metric and inch-pound units, the inch-pound units shall rule.

FIGURE 1. Case outline.

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Terminal number	Terminal symbol	Function	Description	Burn-in Connection
1	V _L	SUPPLY	Output pull-up supply	+20 V
2	NED	OUTPUT	NED pulsed output	NC
3	NC3	NC	No connection	NC
4	C _B	INPUT	Timing capacitor (negative)	0 V
5	C _A	OUTPUT	Timing capacitor (positive)	NC
6	TEST	INPUT	Built in Test input	0 V
7	GND	GROUND	Device supply ground and case connection	0 V
8	V _B	SUPPLY	Device detector bias supply	+5.5 V
9	R _{TH}	INPUT	Threshold set input	0 V
10	NC10	NC	No connection	NC
11	NFR	INPUT	Flag reset inverse input	0 V
12	FR	INPUT	Flag reset input	0 V
13	NEF	OUTPUT	NEF output	NC
14	V _H	SUPPLY	Device Supply	+5.5 V

NOTE: Pin 7 is connected to the case.

FIGURE 2. Terminal and Burn-in connections.

TABLE II. Electrical test requirements.

MIL-PRF-38534 test requirements	Subgroups (in accordance with MIL-PRF-38534, group A test table)
Interim electrical parameters	1, 9
Final electrical parameters	1, 2, 3, 9, 10, 11
Group A test requirements	1*, 2, 3, 9, 10, 11
Group C end-point electrical parameters	1, 2, 3, 9
End-point electrical parameters for Radiation Hardness Assurance (RHA) devices	Not applicable

* PDA applies to subgroup 1.

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4.2 Screening. Screening shall be in accordance with MIL-PRF-38534. The following additional criteria shall apply:

a. Burn-in test, method 1015 of MIL-STD-883.

(1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DLA Land and Maritime -VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1015 of MIL-STD-883.

(2) T_A as specified in accordance with table I of method 1015 of MIL-STD-883.

b. Interim and final electrical test parameters shall be as specified in table II herein, except interim electrical parameter tests prior to burn-in are optional at the discretion of the manufacturer.

TABLE III. Truth Table.

STATUS	TEST Input	NFR Input	Time ->	t = 0s	t = 0s	After t ₀	After t _q	After t _p	After t _p	After t _r	After t _s
			FR Input	NED Output	NEF Output	NED Output	NEF Output	NED Output	NEF Output	NEF Output	NEF Output
Standby	L	H	L	H	H	H	H	H	H	H	H
NED (or simulation)	H	H	L	H	H	L	L	H	L	H	H
After NED (or simulation)	L	H	L	L	L	L	L	H	L	H	H
Reset by FR input	L	H	H	H	L	N/A	N/A	N/A	N/A	H	H
Reset by NFR input	L	L	L	H	L	N/A	N/A	N/A	N/A	H	H

NOTES:

1. Time t₀ is the delay between the TEST input voltage rising to 90% of its peak voltage and the NED output falling to 10% of its peak voltage.
2. Time t_p is the width of the pulse from the NED output measured between the falling and rising edges at 50% of the amplitude.
3. Time t_q is the delay between the TEST input voltage rising to 90% of its peak voltage and the NEF output falling to 10% of its peak voltage.
4. Time t_r is the delay between the FR input voltage rising to 90% of its peak voltage and the NEF output rising to 90% of its peak voltage.
5. Time t_s is the delay between the NFR input voltage falling to 10% of its peak voltage and the NEF output rising to 90% of its peak voltage.

4.3 Conformance and periodic inspections. Conformance inspection (CI) and periodic inspection (PI) shall be in accordance with MIL-PRF-38534 and as specified herein.

4.3.1 Group A inspection (CI). Group A inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. Tests shall be as specified in table II herein.
- b. Subgroups 4, 5, 6, 7, and 8 shall be omitted.

4.3.2 Group B inspection (PI). Group B inspection shall be in accordance with MIL-PRF-38534.

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4.3.3 Group C inspection (PI). Group C inspection shall be in accordance with MIL-PRF-38534 and as follows:

- a. End-point electrical parameters shall be as specified in table II herein.
- b. Steady-state life test, method 1005 of MIL-STD-883.
 - (1) Test condition A, B, C, or D. The test circuit shall be maintained by the manufacturer under document revision level control and shall be made available to either DLA Land and Maritime -VA or the acquiring activity upon request. Also, the test circuit shall specify the inputs, outputs, biases, and power dissipation, as applicable, in accordance with the intent specified in method 1005 of MIL-STD-883.
 - (2) T_A as specified in accordance with table I of method 1005 of MIL-STD-883.
 - (3) Test duration: 1,000 hours, except as permitted by method 1005 of MIL-STD-883.

4.3.4 Group D inspection (PI). Group D inspection shall be in accordance with MIL-PRF-38534.

4.3.5 Radiation Hardness Assurance (RHA) inspection. RHA inspection is not currently applicable to this drawing.

5. PACKAGING

5.1 Packaging requirements. The requirements for packaging shall be in accordance with MIL-PRF-38534.

6. NOTES

6.1 Intended use. Microcircuits conforming to this drawing are intended for use for Government microcircuit applications (original equipment), design applications, and logistics purposes.

6.2 Replaceability. Microcircuits covered by this drawing will replace the same generic device covered by a contractor-prepared specification or drawing.

6.3 Configuration control of SMD's. All proposed changes to existing SMD's will be coordinated as specified in MIL-PRF-38534.

6.4 Record of users. Military and industrial users should inform DLA Land and Maritime when a system application requires configuration control and the applicable SMD. DLA Land and Maritime -VA will maintain a record of users and this list will be used for coordination and distribution of changes to the drawings. Users of drawings covering microelectronic devices (FSC 5962) should contact DLA Land and Maritime -VA, telephone (614) 692-8108.

6.5 Comments. Comments on this drawing should be directed to DLA Land and Maritime -VA, Columbus, Ohio 43218-3990, or telephone (614) 692-1081.

6.6 Sources of supply. Sources of supply are listed in MIL-HDBK-103 and QML-38534. The vendors listed in MIL-HDBK-103 and QML-38534 have submitted a certificate of compliance (see 3.7 herein) to DLA Land and Maritime -VA and have agreed to this drawing.

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STANDARD MICROCIRCUIT DRAWING BULLETIN

DATE: 21-06-07

Approved sources of supply for SMD 5962-10220 are listed below for immediate acquisition information only and shall be added to MIL-HDBK-103 and QML-38534 during the next revisions. MIL-HDBK-103 and QML-38534 will be revised to include the addition or deletion of sources. The vendors listed below have agreed to this drawing and a certificate of compliance has been submitted to and accepted by DLA Land and Maritime -VA. This information bulletin is superseded by the next dated revisions of MIL-HDBK-103 and QML-38534. DLA Land and Maritime maintains an online database of all current sources of supply <https://landandmaritimeapps.dla.mil/programs/Smcr/>.

Standard microcircuit drawing PIN <u>1</u> /	Vendor CAGE number	Vendor similar PIN <u>2</u> /
5962-1022001HXA 5962-1022001HXC	U4388 U4388	15313A-DESC 15313-DESC

- 1/ The lead finish shown for each PIN representing a hermetic package is the most readily available from the manufacturer listed for that part. If the desired lead finish is not listed contact the Vendor to determine its availability.
- 2/ Caution. Do not use this number for item acquisition. Items acquired to this number may not satisfy the performance requirements of this drawing.

Vendor CAGE
number

U4388

Vendor name
and address

API Microelectronics LTD
Fenner Road, South Denes
Great Yarmouth
NR30 3PX
Norfolk
United Kingdom

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